Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S77	4168	bond$4 near15 prob$4 near15 (area or pad) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 16:07
S76	9743	bond$4 same prob$4 same (area or pad) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 16:07
S75	26714	bond$4 same prob$4 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 16:07
S74	27544	bond$4 same prob$ and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 16:07
S73	2440	bond same probe and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 16:07
S80	755	bond$4 near15 (probe or probing or probes) near15 (area or pad) and semiconductor and @py<"2001"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 16:09
S79	1471	bond$4 near15 prob$3 near15 (area or pad) and semiconductor and @py<"2001"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 16:09
S78	1719	bond$4 near15 prob$4 near15 (area or pad) and semiconductor and @py<"2001"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 16:09
S82	862	semiconductor near5 chip near5 scrib$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 10:55
S81	2683	chip near5 scrib$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 10:55

S83	8	semiconductor near5 chip near5 scrib$3 near15 bond	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 10:57
S84	554	semiconductor near5 chip near5 scrib$3 near15 wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 11:00
S87	2228	bond$4 same prob$6 same line and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 11:04
S86	5488	bond$4 same prob$6 same line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 11:04
S85	29	semiconductor near5 chip near5 scrib$3 near15 prob$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 11:04
S88	337	bond$4 same prob$6 same line same (via or hole) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 11:06
S90	4	("6451681" "6373143").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 11:14
S89	141	bond$4 same (probe probes or probing or probed) same line same (via or hole) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 11:14
S91	6	("5134460" | "5731624" | "5795819" | "5864946" | "6133136" | "6187680"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/13 11:21
S97	174	semiconductor near5 chip near5 plural$6 near5 adjacent	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/13 11:22
S96	10476	semiconductor near5 chip near5 plural$6	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/13 11:22

S95	12879	semiconductor near5 chip near15 plural$6	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/13 11:22
S94	64201	semiconductor near5 chip near15 chip	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/13 11:22
S93	63946	semiconductor near5 chip near10 chip	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/13 11:22
S92	123709	chip near10 chip	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/13 11:22
S98	192	bond$4 near15 metal near5 line near15 (via or hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 11:38
S99	84	bond$4 near15 metal near5 line near15 (via or hole) and @py<"2002"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 11:43
S101	198	bond$4 near S82 pad near15 metal near2 line near15 (via or hole) and @py<"2002"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 11:44
S100	238	bond$4 near S82 pad near15 metal near5 line near15 (via or hole) and @py<"2002"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 11:44
S103	2	"6075292".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 12:04
S102	38	bond$4 near2 pad near15 metal near2 line near15 (via or hole) and @py<"2002"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 12:04
S105	2953	bond near2 pad near10 (via or hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 12:09

S104	22	gerald near2 friese.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 12:09
S106	40	bond near2 pad near10 (via or hole) near15 barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 12:10